

Complementary Power Transistors

DPAK for Surface Mount Applications

MJD41C (NPN), MJD42C (PNP)

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves ("1" Suffix)
- Electrically Similar to Popular TIP41 and TIP42 Series
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS

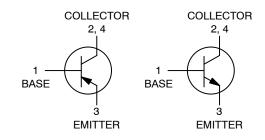
Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	100	Vdc
Collector-Base Voltage	V _{CB}	100	Vdc
Emitter-Base Voltage	V _{EB}	5	Vdc
Collector Current – Continuous	I _C	6	Adc
Collector Current - Peak	I _{CM}	10	Adc
Base Current	Ι _Β	2	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	20 0.16	W W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.75 0.014	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C
ESD - Human Body Model	HBM	3B	V
ESD – Machine Model	MM	С	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

 These ratings are applicable when surface mounted on the minimum pad sizes recommended.

SILICON POWER TRANSISTORS 6 AMPERES 100 VOLTS, 20 WATTS

COMPLEMENTARY



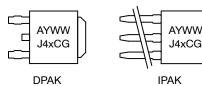


3
DPAK
CASE 369C
STYLE 1



IPAK CASE 369D STYLE 1

MARKING DIAGRAMS



A = Assembly Location
Y = Year
WW = Work Week

J4xC = Device Code x = 1 or 2 G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 5.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	6.25	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	71.4	°C/W

^{2.} These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

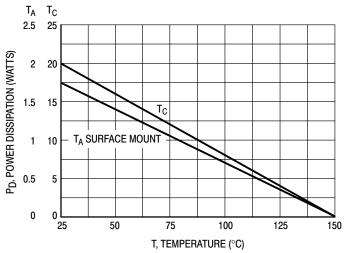
Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	,			
Collector–Emitter Sustaining Voltage (Note 3) $(I_C = 30 \text{ mAdc}, I_B = 0)$	V _{CEO(sus)}	100	-	Vdc
Collector Cutoff Current (V _{CE} = 60 Vdc, I _B = 0)	ICEO	-	50	μAdc
Collector Cutoff Current (V _{CE} = 100 Vdc, V _{EB} = 0)	I _{CES}	-	10	μAdc
Emitter Cutoff Current (V _{BE} = 5 Vdc, I _C = 0)	I _{EBO}	-	0.5	mAdc
ON CHARACTERISTICS (Note 3)				•
DC Current Gain ($I_C = 0.3$ Adc, $V_{CE} = 4$ Vdc) ($I_C = 3$ Adc, $V_{CE} = 4$ Vdc)	h _{FE}	30 15	- 75	-
Collector–Emitter Saturation Voltage (I _C = 6 Adc, I _B = 600 mAdc)	V _{CE(sat)}	-	1.5	Vdc
Base-Emitter On Voltage (I _C = 6 Adc, V _{CE} = 4 Vdc)	V _{BE(on)}	-	2	Vdc
DYNAMIC CHARACTERISTICS			•	•
Current Gain – Bandwidth Product (Note 4) (I _C = 500 mAdc, V _{CE} = 10 Vdc, f _{test} = 1 MHz)	f _T	3	-	MHz
Small–Signal Current Gain ($I_C = 0.5$ Adc, $V_{CE} = 10$ Vdc, $f = 1$ kHz)	h _{fe}	20	-	-

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics for the listed test conditions.

3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

4. $f_T = |h_{fe}| \bullet f_{test}$.

TYPICAL CHARACTERISTICS



V_{CC} +30 V ₹R_C 25 μs → SCOPE R_{B} D₁ 51 $t_r,\,t_f \leq 10\;ns$ **DUTY CYCLE = 1%**

 R_{B} and R_{C} VARIED TO OBTAIN DESIRED CURRENT LEVELS D₁ MUST BE FAST RECOVERY TYPE, e.g.: MSB5300 USED ABOVE $I_{B} \approx 100 \ mA$ MSD6100 USED BELOW $I_B \approx 100 \ mA$ REVERSE ALL POLARITIES FOR PNP.

Figure 1. Power Derating

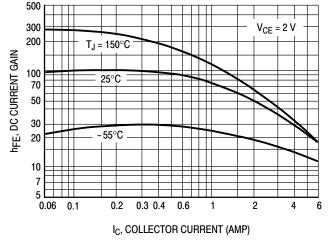


Figure 2. Switching Time Test Circuit

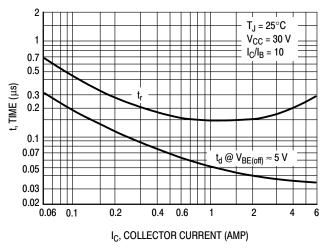


Figure 3. DC Current Gain

Figure 4. Turn-On Time

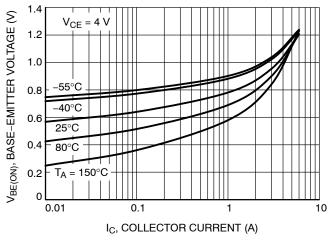


Figure 5. Base Emitter Voltage vs. Collector Current

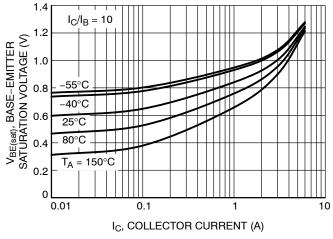


Figure 6. Base Emitter Saturation Voltage vs. **Collector Current**

TYPICAL CHARACTERISTICS

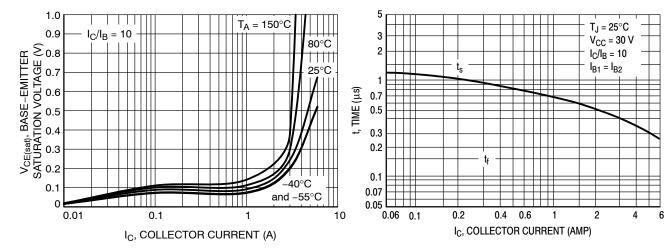


Figure 7. Collector Emitter Saturation Voltage vs. Collector Current

Figure 8. Turn-Off Time

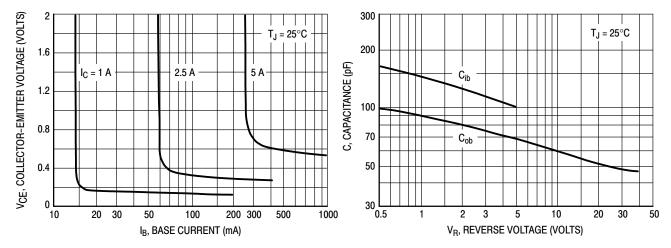


Figure 9. Collector Saturation Region

Figure 10. Capacitance

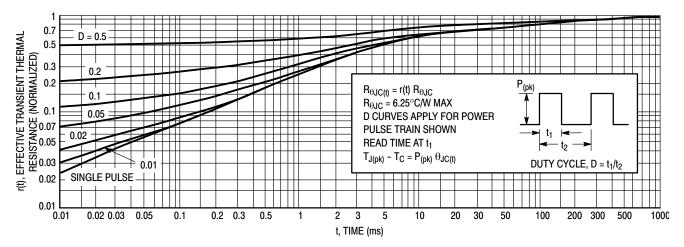


Figure 11. Thermal Response

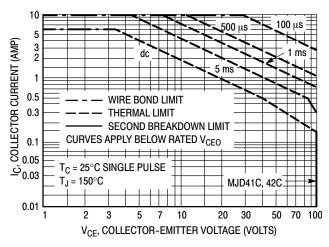


Figure 12. Maximum Forward Bias Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on $T_{J(pk)} = 150^{\circ} C$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ} C$. $T_{J(pk)}$ may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

ORDERING INFORMATION

Device	Package Type	Package	Shipping [†]
MJD41CRLG	DPAK (Pb-Free)	369C	1,800 / Tape & Reel
MJD41CT4G	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD41CT4G*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
MJD42CG	DPAK (Pb-Free)	369C	75 Units / Rail
MJD42CRLG	JD42CRLG DPAK (Pb-Free)		1,800 / Tape & Reel
NJVMJD42CRLG*	DPAK (Pb-Free)	369C	1,800 / Tape & Reel
MJD42CT4G	DPAK (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD42CT4G*	DPAK (Pb-Free)	369C	2,500 / Tape & Reel

DISCONTINUED (Note 5)

MJD42C1G	IPAK	369D	75 Units / Rail
	(Pb-Free)		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

^{5.} **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on www.onsemi.com.

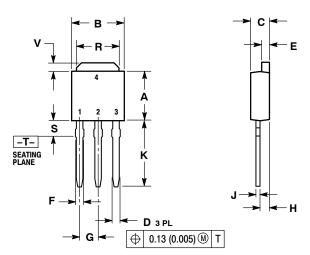


DPAK INSERTION MOUNT

CASE 369 ISSUE O

DATE 02 JAN 2000





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.250	5.97	6.35
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
Е	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.090	BSC	2.29 BSC	
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.175	0.215	4.45	5.46
S	0.050	0.090	1.27	2.28
V	0.030	0.050	0.77	1 27

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:		STYLE 5:		STYLE 6:	
PIN 1.	BASE	PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	GATE	PIN 1.	MT1
2.	COLLECTOR	2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE	2.	MT2
3.	EMITTER	3.	SOURCE	3.	ANODE	3.	GATE	3.	CATHODE	3.	GATE
4.	COLLECTOR	4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE	4.	MT2

DOCUMENT NUMBER:	98ASB42319B	Electronic versions are uncontrolled except when accessed directly from the Document Repos Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	DPAK INSERTION MOUNT		PAGE 1 OF 1		

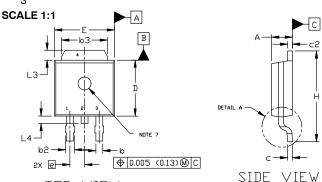
onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.



DPAK (SINGLE GAUGE)

CASE 369C **ISSUE G**

DATE 31 MAY 2023





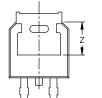
- DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994. CONTROLLING DIMENSION: INCHES
- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS 63,
- L3. AND Z. L3, AND Z.

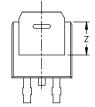
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR
 GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 DIMENSIONS D AND E ARE DETERMINED AT THE
 OUTERMOST EXTREMES OF THE PLASTIC BODY.
 DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
 DETININAL MOLD ESCALUPE.

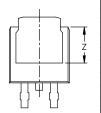
- OPTIONAL MOLD FEATURE.

DIM	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
C	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090	BSC	5.29 B2C	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

TOP VIEW







BOTTOM VIEW

2.58

[0.102]

1.60

[0.063]

5.80

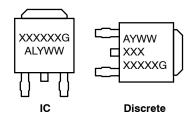
[0.228]

BOTTOM VIEW ALTERNATE CONSTRUCTIONS

6.20 -L2 GAUGE PLANE [0.244] 3.00 [0.118]

DETAIL A ROTATED 90° CW

GENERIC MARKING DIAGRAM*



XXXXXX	= Device Code
Α	= Assembly Location
L	= Wafer Lot
Υ	= Year
WW	= Work Week
G	= Pb-Free Package

RECOMMENDED MOUNTING FOOTPRINT* *FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DUWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

6.17 [0.243]

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:	STYLE 5:
PIN 1. BASE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. GATE
COLLECTOR	2. DRAIN	CATHODE	2. ANODE	2. ANODE
EMITTER	SOURCE	ANODE	3. GATE	CATHODE
COLLECTOR	DRAIN	CATHODE	4. ANODE	ANODE

STYLE 6:	STYLE 7	STYLE 8:	STYLE 9:	STYLE 10:
0	0	0	011220.	
PIN 1. MT1	PIN 1. GATE	PIN 1. N/C	PIN 1. ANODE	PIN 1. CATHODE
2. MT2	2. COLLECTOR	2. CATHODE	2. CATHODE	ANODE
GATE	EMITTER	ANODE	RESISTOR ADJUST	CATHODE
4. MT2	COLLECTOR	CATHODE	4. CATHODE	ANODE

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON10527D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	DPAK (SINGLE GAUGE)		PAGE 1 OF 1	

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales

Mouser Electronics

Λ	uth	ariza	~~ ~	iatri	huta	
н	uun	orize	ധ	ISITI	ונוכו)[

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

onsemi:

MJD41CRL MJD41CRLG MJD41CT4 MJD41CT4G MJD42C MJD42C1 MJD42CRLG MJD42CT4 MJD42CT4G NJVMJD42CT4G NJVMJD42CT4G NJVMJD42CRLG